Vishay Siliconix

# P-Channel 30 V (D-S) MOSFET



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	-30			
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS}$ = -10 V	0.0095			
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -4.5 \text{ V}$	0.0150			
Q <sub>g</sub> typ. (nC)	31			
I <sub>D</sub> (A) <sup>a</sup>	-19.3			
Configuration	Single			

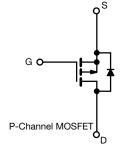
#### **FEATURES**

- TrenchFET® Gen III p-channel power MOSFET
- 100% R<sub>g</sub> tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



### **APPLICATIONS**

- Adaptor switch
- Power management
- · Load switch



ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	Si4153DY-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V <sub>DS</sub>	-30	V
Gate-source voltage		V <sub>GS</sub>	± 25	V
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C		-19.3	
	T <sub>C</sub> = 70 °C	1 , [	-15.4	
	T <sub>A</sub> =25 °C	I <sub>D</sub>	-14.3 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		-11.4 <sup>b, c</sup>	^
Pulsed drain current (t = 100 µs)		I <sub>DM</sub>	-100	Α
Continuous source-drain diode current	T <sub>C</sub> = 25 °C		-5.1	
	T <sub>A</sub> = 70 °C	I <sub>S</sub>	-3.3 b, c	
Single pulse avalanche current	1 0.1 ml l	I <sub>AS</sub>	-15	
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	11.25	mJ
Maximum power dissipation	T <sub>C</sub> = 25 °C		5.6	
	T <sub>C</sub> = 70 °C		3.6	14/
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.1 <sup>b, c</sup>	W
	T <sub>A</sub> = 70 °C	1	2.0 b, c	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	
Soldering recommendations (peak temperature) d, e			260	°C

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, d	t ≤ 10 s	R <sub>thJA</sub>	34	40	°C/W	
Maximum junction-to-case (drain)	Steady state	R <sub>thJF</sub>	18	22	C/VV	

#### Notes

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. Maximum under steady state conditions is 85 °C/W
- e.  $T_C = 25$  °C



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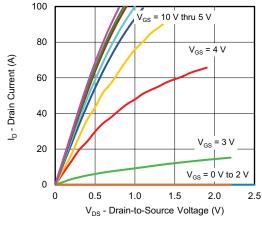
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	1 050 4	-	-21	-	m\//°C	
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = -250 μA	-	3.8	-	mV/°C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1	-	-2.5	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$	-	=	± 100	nA	
Zero gate voltage drain current		V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V	-	-	-1	μA	
	I <sub>DSS</sub>	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C	-	-	-15		
During and the state of the sta	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -10 A	-	0.0072	0.0095		
Drain-source on-state resistance <sup>a</sup>		V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -10 A	-	0.0120	0.0150	Ω	
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -10 A	-	44	-	S	
Dynamic <sup>b</sup>			•				
Input capacitance	C <sub>iss</sub>		-	3600	-	pF	
Output capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	430	-		
Reverse transfer capacitance	C <sub>rss</sub>		-	390	-		
Tatal asta shaws	0	V <sub>DS</sub> = -15 V, V <sub>GS</sub> = -10 V, I <sub>D</sub> = -10 A	-	62	93	nC	
Total gate charge	$Q_g$	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$	-	31	47		
Gate-source charge	$Q_{gs}$	V 45VV 45VI 40A	-	9.2	-		
Gate-drain charge	Q <sub>gd</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -10 \text{ A}$	-	10.8	-		
Gate resistance	$R_g$	f = 1 MHz	0.5	1.9	3.5	Ω	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD} = -15 \text{ V}, R_L = 1.5 \Omega, I_D \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	50	100		
Rise time	t <sub>r</sub>		-	46	90		
Turn-off delay time	t <sub>d(off)</sub>		-	35	70		
Fall time	t <sub>f</sub>		-	15	30		
Turn-on delay time	t <sub>d(on)</sub>		-	13	25	ns	
Rise time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_L = 1.5 \Omega, I_D \cong -10 \text{ A},$	-	10	20		
Turn-off delay time	t <sub>d(off)</sub>	$V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	36	70		
Fall time	t <sub>f</sub>		-	10	20		
<b>Drain-Source Body Diode Characteristi</b>	cs						
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	-5.1	^	
Pulse diode forward current	I <sub>SM</sub>		-	-	-100	A	
Body diode voltage	$V_{SD}$	$I_S = -5 \text{ A}, V_{GS} = 0 \text{ V}$	-	-0.75	-1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = -10 A, di/dt = 100 A/μs,	-	30	60	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>		-	11	22	nC	
Reverse recovery fall time	t <sub>a</sub>	$T_J = 25  ^{\circ}\text{C}$	-	8	-	İ	
Reverse recovery rise time	t <sub>b</sub>		_	22	_	ns	

#### Notes

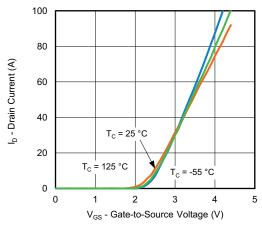
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

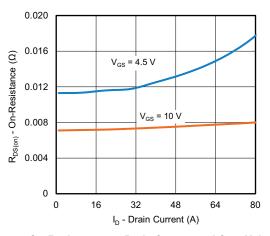




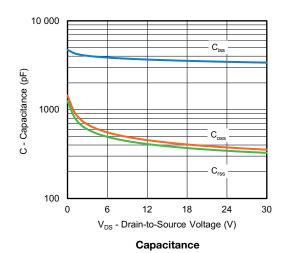
**Output Characteristics** 

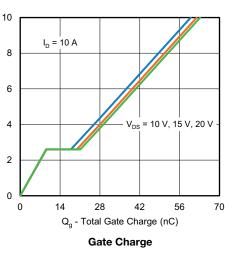


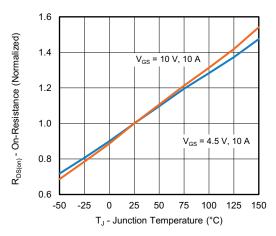
**Transfer Characteristics** 



On-Resistance vs. Drain Current and Gate Voltage

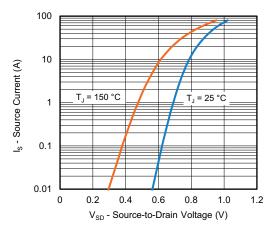




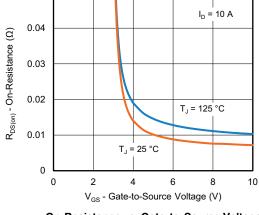


On-Resistance vs. Junction Temperature

V<sub>GS</sub> - Gate-to-Source Voltage (V)

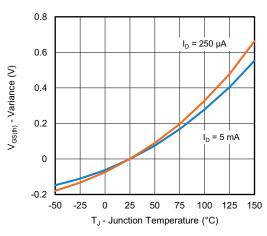


#### Source-Drain Diode Forward Voltage

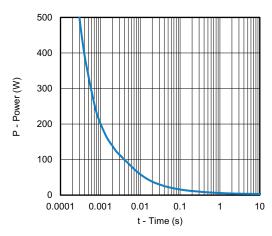


0.05

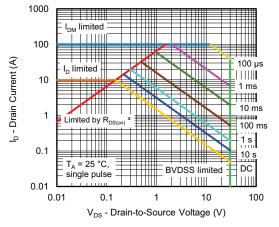
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



Single Pulse Power, Junction-to-Ambient



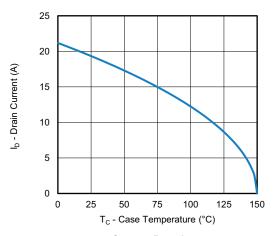
Safe Operating Area, Junction-to-Ambient

#### Note

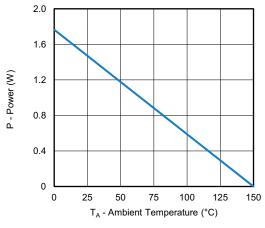
a.  $V_{GS} > minimum V_{GS}$  at which  $R_{DS(on)}$  is specified

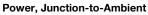
S21-1169-Rev. A, 29-Nov-2021

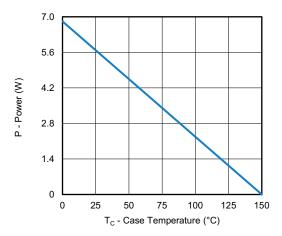




### Current Derating a





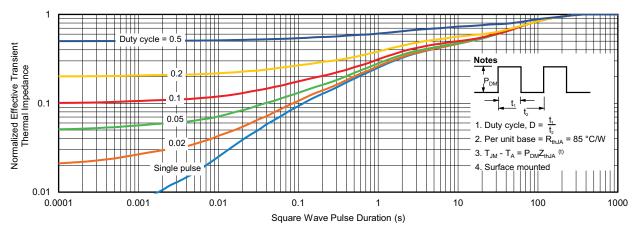


Power, Junction-to-Case

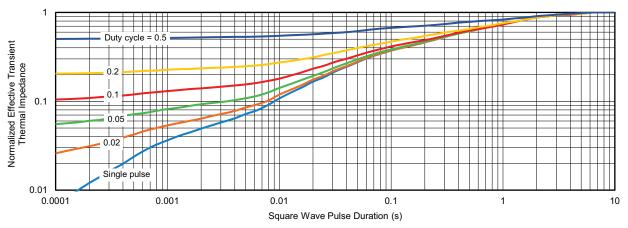
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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